



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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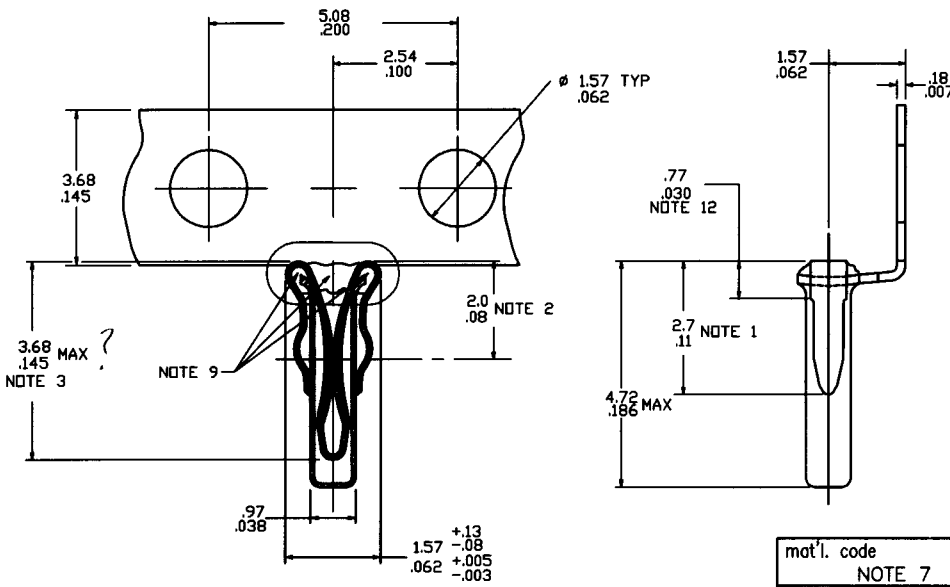
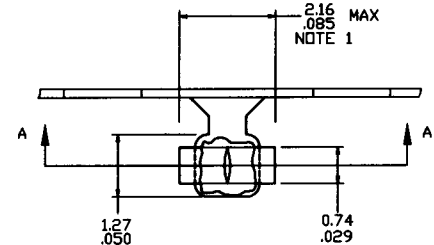


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PRODUCT NUMBER	QTY/REEL	REMARKS
75060-012	25 M	
-013	5 M	
-016	25 M	NOTE 10
75060-017	5 M	NOTE 10

- NOTES:
- ① DIMENSIONS APPLY PRIOR TO INSTALLATION.
 - ② SHOWS CENTERLINE OF THEORETICAL POINT OF CONTACT FROM TOP OF SPRING.
 - ③ SHOWS MAX DEPTH FOR .51/.020 LEAD FROM TOP OF SPRING.
 - ④ THE SOCKET ASS'Y SHALL BE MACHINE INSERTABLE AND SELF-RETAINING DURING WAVE SOLDERING IN HOLES FROM 1.27/.050 TO 1.47/.058 DIA.
 5. THE SPRING SHALL SOLDER TO THE CUP DURING WAVE SOLDERING IN SINGLE OR DOUBLE SIDED BOARDS TO 1.57/.062 THK. NO SOLDER SHALL ENTER CUP.
 6. THE SOCKET SHALL ACCEPT ROUND LEADS FROM .30/.012 TO .56/.022 DIA AND FLAT LEADS WHEN PROPERLY ORIENTED. FROM .20/.008 TO .39/.015 THK BY .38/.015 TO .58/.023 WIDE.
 7. CUP MATERIAL: GILDING MATERIAL PER MIL C21768. SPRING MATERIAL: BeCu PER CC-C-533
 8. CUP PLATING: TIN-LEAD 60/40 .76μ/30μ' MIN THK
SPRING PLATING: .76μ/30μ' Au(MIL-G-45204B) TYPE IC OVER 1.01μ/40μ' NICKEL(QQ-N-290)
 - ⑨ RTV APPLIED TO AREA SHOWN TO PREVENT FLUX AND SOLDER FROM ENTERING SOCKET DURING WAVE SOLDERING.
 - ⑩ RTV TO BE PLACED IN SPRING LOOPS ONLY.
11. SEE PRODUCT SPECIFICATION NO 12-006 FOR INSERTION/WITHDRAWAL FORCES.
 12. .77/.030 DIM REFERS TO INSTALLED HEIGHT ABOVE BOARD.



SECTION A-A

mat'l. code NOTE 7		tolerances unless otherwise specified		CUSTOMER COPY	Electronics FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.XX ±.01/.3	projection
J		RLS	5/8/87		.XXX ±.005/0.13	title
K	V90943	DLH	4/22/99	angles	.XXX ±.0020/0.051	MINISERT SOCKET ASSY
					0° ±2°	product family
				dr	R. SEIPLE 5/8/87	code
				enr	H. SUNDAY 5/8/87	size
				chr	H. SUNDAY 5/8/87	dwg no
				appd	H. SUNDAY 5/8/87	75060
sheet index	revision sheet	K	1	scale	20/1	code
						22526

ACAD

PDM: Rev:K

STATUS: Released

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